

Product / Process Change Notice

Parts Affected:

All discrete semiconductor devices manufactured in the SOT-523 package.

Extent of Change:

Copper wire has been added as a qualified material for wire bonding in addition to the currently used gold wire.

Reason for Change:

This change will insure an uninterrupted flow of product and provide increased flexibility for supply chain management.

Effect of Change:

This change does not affect the form, fit, or function of any device. Devices assembled with gold wire will continue to be manufactured concurrently with devices assembled with copper wire.

Qualification:

Standard evaluation and qualifications completed resulting in no performance differences compared to current product.

Effective Date of Change:

October 22, 2012.

Sample Availability:

Please contact Salesperson or Manufacturer's Representative.

Part Numbers Affected:

BC846AT	CMUDM8005	CMUT2222A
BC846BT	CMUD2836	CMUT2907A
BC847AT	CMUD2838	CMUT3410
BC847BT	CMUD4448	CMUT3904
BC847CT	CMUD6263AE	CMUT3906
BC856AT	CMUD6263CE	CMUT4401
BC856BT	CMUD6263E	CMUT4403
BC857AT	CMUD6263SE	CMUT5087E
BC857BT	CMUD7000	CMUT5088E
BC857CT	CMUSH05-4	CMUT5179
CMUDM7001	CMUSH2-4	CMUT5401
CMUDM7004	CMUSH2-4A	CMUT5401E
CMUDM7005	CMUSH2-4C	CMUT5551
CMUDM8001	CMUSH2-4L	CMUT5551E
CMUDM8004	CMUSH2-4S	CMUT7410